

ELECTRICAL CONNECTION WITH INWARDLY DEFORMABLE CONTACTS

CROSS REFERENCE TO RELATED APPLICATIONS

7/27/05
[0001] The present application is a divisional application of United States Patent Application Serial No. 10/200,941, filed July 23, 2002, which is ^{us pat. 6,706,973} a divisional application of United States Patent Application Serial No. 09/779,117, filed February 8, 2001, which is ^{us pat. 6,700,072} a divisional application of United States Patent Application No. 08/989,305, filed December 12, 1997, now United States Patent No. 6,247,228, which claims the benefit of Provisional Patent Application No. 60/032,884, filed December 13, 1996, which applications are hereby incorporated by reference in their entirety herein.

BACKGROUND OF THE INVENTION

[0002] The present invention relates to the field of electrical circuitry, and more particularly relates to layered circuit structures such as multilayer circuit boards, to components and methods utilized in fabrication of such structures and to methods of making the same.

[0003] Electrical components are commonly mounted on circuit panel structures such as printed circuit boards. Circuit panels ordinarily include a generally flat sheet of dielectric material with electrical conductors disposed on a major, flat surface of the sheet or on both major surfaces. The conductors are commonly formed from metallic materials such as copper and serve to interconnect the electrical components mounted to the board. Where the conductors are